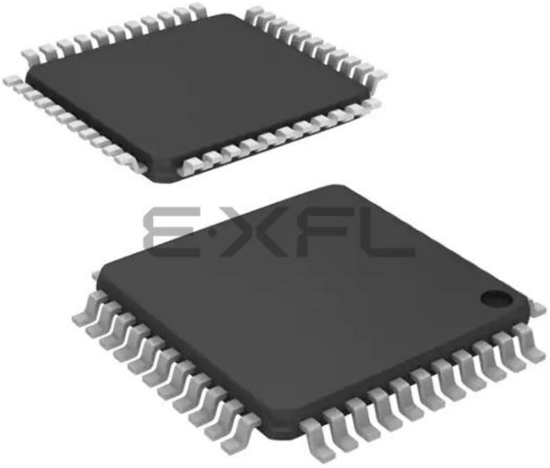

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	72MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, HLVD, I²S, POR, PWM, WDT
Number of I/O	34
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 3.6V
Data Converters	A/D 13x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx254f128dt-i-pt

TABLE 1-2: OSCILLATOR PINOUT I/O DESCRIPTIONS

Pin Name	Pin Number(1)			Pin Type	Buffer Type	Description
	28-pin QFN	28-pin SOIC	44-pin QFN/ TQFP			
Oscillators						
CLKI	6	9	30	I	ST/CMOS	External clock source input. Always associated with OSC1 pin function.
CLKO	7	10	31	O	—	Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. Optionally functions as CLKO in RC and EC modes. Always associated with OSC2 pin function.
OSC1	6	9	30	I	ST/CMOS	Oscillator crystal input. ST buffer when configured in RC mode; CMOS otherwise.
OSC2	7	10	31	O	—	Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. Optionally functions as CLKO in RC and EC modes.
SOSCI	8	11	33	I	ST/CMOS	32.768 kHz low-power oscillator crystal input; CMOS otherwise.
SOSCO	9	12	34	O	—	32.768 kHz low-power oscillator crystal output.
REFCLKI	PPS	PPS	PPS	I	ST	Reference Input Clock
REFCLKO	PPS	PPS	PPS	O	—	Reference Output Clock

Legend: CMOS = CMOS compatible input or output
ST = Schmitt Trigger input with CMOS levels
TTL = TTL input buffer
Analog = Analog input
O = Output
PPS = Peripheral Pin Select
P = Power
I = Input
— = N/A

Note 1: Pin numbers are provided for reference only. See the **“Pin Diagrams”** section for device pin availability.

TABLE 1-3: IC1 THROUGH IC5 PINOUT I/O DESCRIPTIONS

Pin Name	Pin Number(1)			Pin Type	Buffer Type	Description
	28-pin QFN	28-pin SOIC	44-pin QFN/ TQFP			
Input Capture						
IC1	PPS	PPS	PPS	I	ST	Input Capture Input 1-5
IC2	PPS	PPS	PPS	I	ST	
IC3	PPS	PPS	PPS	I	ST	
IC4	PPS	PPS	PPS	I	ST	
IC5	PPS	PPS	PPS	I	ST	

Legend: CMOS = CMOS compatible input or output
ST = Schmitt Trigger input with CMOS levels
TTL = TTL input buffer
Analog = Analog input
O = Output
PPS = Peripheral Pin Select
P = Power
I = Input
— = N/A

Note 1: Pin numbers are provided for reference only. See the **“Pin Diagrams”** section for device pin availability.

2.0 GUIDELINES FOR GETTING STARTED WITH 32-BIT MCUs

> **Note:** This data sheet summarizes the features of the PIC32MX1XX/2XX 28/44-pin XLP Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the documents listed in the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

2.1 Basic Connection Requirements

Getting started with the PIC32MX1XX/2XX 28/44-pin XLP Family of 32-bit Microcontrollers (MCUs) requires attention to a minimal set of device pin connections before proceeding with development. The following is a list of pin names, which must always be connected:

- All VDD and VSS pins (see **2.2 “Decoupling Capacitors”**)
- All AVDD and AVSS pins, even if the ADC module is not used (see **2.2 “Decoupling Capacitors”**)
- VCAP pin (see **2.3 “Capacitor on Internal Voltage Regulator (VCAP)”**)
- $\overline{\text{MCLR}}$ pin (see **2.4 “Master Clear (MCLR) Pin”**)
- PGECx/PGEDx pins, used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes (see **2.5 “ICSP Pins”**)
- OSC1 and OSC2 pins, when external oscillator source is used (see **2.7 “External Oscillator Pins”**)

The following pins may be required:

- VREF+/VREF- pins – used when external voltage reference for the ADC module is implemented

> **Note:** The AVDD and AVSS pins must be connected, regardless of ADC use and the ADC voltage reference source.

2.2 Decoupling Capacitors

The use of decoupling capacitors on power supply pins, such as VDD, VSS, AVDD and AVSS is required. See Figure 2-1.

Consider the following criteria when using decoupling capacitors:

- **Value and type of capacitor:** A value of 0.1 µF (100 nF), 10-20V is recommended. The capacitor should be a low Equivalent Series Resistance (low-ESR) capacitor and have resonance frequency in the range of 20 MHz and higher. It is further recommended that ceramic capacitors be used.
- **Placement on the printed circuit board:** The decoupling capacitors should be placed as close to the pins as possible. It is recommended that the capacitors be placed on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is within one-quarter inch (6 mm) in length.
- **Handling high frequency noise:** If the board is experiencing high frequency noise, upward of tens of MHz, add a second ceramic-type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 µF to 0.001 µF. Place this second capacitor next to the primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible. For example, 0.1 µF in parallel with 0.001 µF.
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum thereby reducing PCB track inductance.

2.8.1 CRYSTAL OSCILLATOR DESIGN CONSIDERATION

The following example assumptions are used to calculate the Primary Oscillator loading capacitor values:

- C_{IN} = PIC32_OSC2_Pin Capacitance = ~4-5 pF
- C_{OUT} = PIC32_OSC1_Pin Capacitance = ~4-5 pF
- C1 and C2 = XTAL manufacturing recommended loading capacitance
- Estimated PCB stray capacitance, (i.e.,12 mm length) = 2.5 pF

EXAMPLE 2-1: CRYSTAL LOAD CAPACITOR CALCULATION

Crystal manufacturer recommended: $C1 = C2 = 15\ pF$

Therefore:

$$C_{LOAD} = \{([C_{IN} + C1] * [C_{OUT} + C2]) / [C_{IN} + C1 + C2 + C_{OUT}]\}$$
$$+ \text{ estimated oscillator PCB stray capacitance}$$
$$= \{([5 + 15][5 + 15]) / [5 + 15 + 15 + 5]\} + 2.5\ pF$$
$$= \{([20][20]) / [40]\} + 2.5$$
$$= 10 + 2.5 = 12.5\ pF$$

Rounded to the nearest standard value or 13 pF in this example for Primary Oscillator crystals “C1” and “C2”.

The following tips are used to increase oscillator gain, (i.e., to increase peak-to-peak oscillator signal):

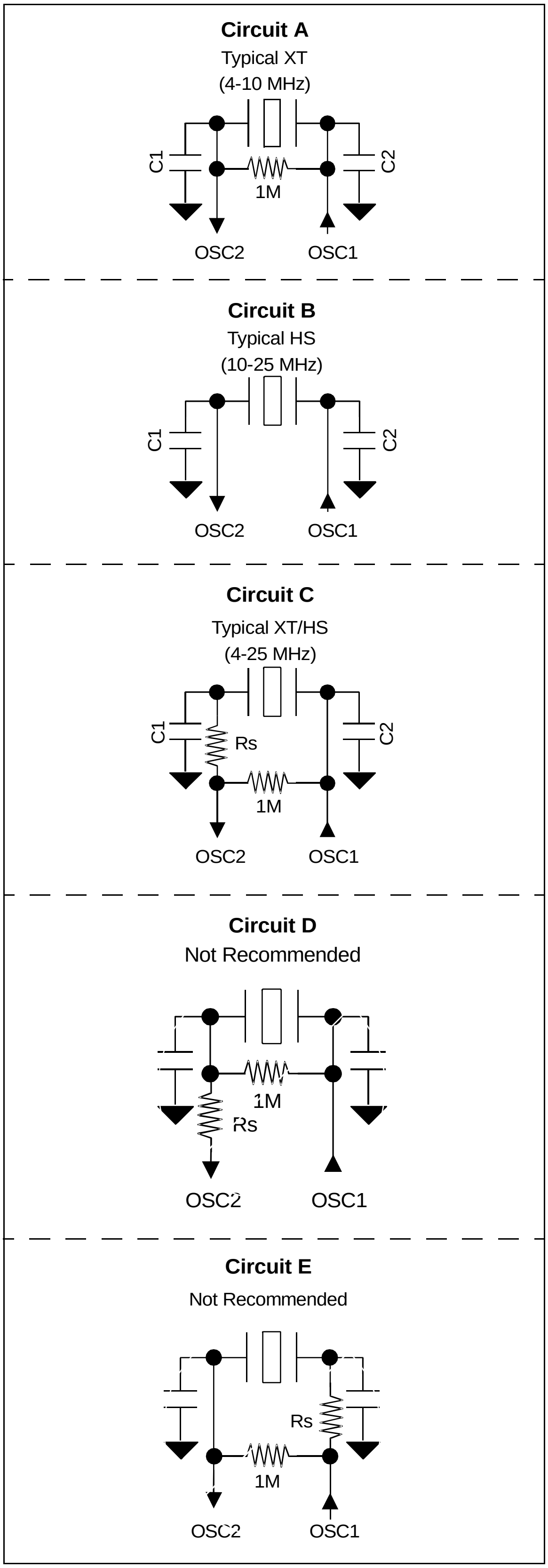
- Select a crystal with a lower “minimum” power drive rating
- Select an crystal oscillator with a lower XTAL manufacturing “ESR” rating.
- Add a parallel resistor across the crystal. The smaller the resistor value the greater the gain. It is recommended to stay in the range of 600k to 1M
- C1 and C2 values also affect the gain of the oscillator. The lower the values, the higher the gain.
- C2/C1 ratio also affects gain. To increase the gain, make C1 slightly smaller than C2, which will also help start-up performance.

> **Note:** Do not add excessive gain such that the oscillator signal is clipped, flat on top of the sine wave. If so, you need to reduce the gain or add a series resistor, RS, as shown in circuit “C” in Figure 2-4. Failure to do so will stress and age the crystal, which can result in an early failure. Adjust the gain to trim the max peak-to-peak to ~V_{DD}-0.6V. When measuring the oscillator signal you must use a FET scope probe or a probe with ≤ 1.5 pF or the scope probe itself will unduly change the gain and peak-to-peak levels.

2.8.1.1 Additional Microchip References

- AN588 *“PICmicro® Microcontroller Oscillator Design Guide”*
- AN826 *“Crystal Oscillator Basics and Crystal Selection for rfPIC™ and PICmicro® Devices”*
- AN849 *“Basic PICmicro® Oscillator Design”*

FIGURE 2-4: PRIMARY CRYSTAL OSCILLATOR CIRCUIT RECOMMENDATIONS



3.2 Architecture Overview

The MIPS32 M4K processor core contains several logic blocks working together in parallel, providing an efficient high-performance computing engine. The following blocks are included with the core:

- Execution Unit
- Multiply/Divide Unit (MDU)
- System Control Coprocessor (CP0)
- Fixed Mapping Translation (FMT)
- Dual Internal Bus interfaces
- Power Management
- MIPS16e® Support
- Enhanced JTAG (EJTAG) Controller

3.2.1 EXECUTION UNIT

The MIPS32 M4K processor core execution unit implements a load/store architecture with single-cycle ALU operations (logical, shift, add, subtract) and an autonomous multiply/divide unit. The core contains thirty-two 32-bit General Purpose Registers (GPRs) used for integer operations and address calculation. The register file consists of two read ports and one write port and is fully bypassed to minimize operation latency in the pipeline.

The execution unit includes:

- 32-bit adder used for calculating the data address
- Address unit for calculating the next instruction address
- Logic for branch determination and branch target address calculation
- Load aligner
- Bypass multiplexers used to avoid stalls when executing instruction streams where data producing instructions are followed closely by consumers of their results
- Leading Zero/One detect unit for implementing the `CLZ` and `CLO` instructions
- Arithmetic Logic Unit (ALU) for performing bitwise logical operations
- Shifter and store aligner

3.2.2 MULTIPLY/DIVIDE UNIT (MDU)

The MIPS32 M4K processor core includes a Multiply/Divide Unit (MDU) that contains a separate pipeline for multiply and divide operations. This pipeline operates in parallel with the Integer Unit (IU) pipeline and does not stall when the IU pipeline stalls. This allows MDU operations to be partially masked by system stalls and/or other integer unit instructions.

The high-performance MDU consists of a 32x16 booth recoded multiplier, result/accumulation registers (HI and LO), a divide state machine, and the necessary multiplexers and control logic. The first number shown (‘32’ of 32x16) represents the *rs* operand. The second number (‘16’ of 32x16) represents the *rt* operand. The PIC32 core only checks the value of the latter (*rt)* operand to determine how many times the operation must pass through the multiplier. The 16x16 and 32x16 operations pass through the multiplier once. A 32x32 operation passes through the multiplier twice.

The MDU supports execution of one 16x16 or 32x16 multiply operation every clock cycle; 32x32 multiply operations can be issued every other clock cycle. Appropriate interlocks are implemented to stall the issuance of back-to-back 32x32 multiply operations. The multiply operand size is automatically determined by logic built into the MDU.

Divide operations are implemented with a simple 1 bit per clock iterative algorithm. An early-in detection checks the sign extension of the dividend (*rs*) operand. If *rs* is 8 bits wide, 23 iterations are skipped. For a 16-bit wide *rs*, 15 iterations are skipped and for a 24-bit wide *rs*, 7 iterations are skipped. Any attempt to issue a subsequent `MDU` instruction while a divide is still active causes an IU pipeline stall until the divide operation is completed.

Table 3-1 lists the repeat rate (peak issue rate of cycles until the operation can be reissued) and latency (number of cycles until a result is available) for the PIC32 core multiply and divide instructions. The approximate latency and repeat rates are listed in terms of pipeline clocks.

TABLE 3-1: MIPS32® M4K® PROCESSOR CORE HIGH-PERFORMANCE INTEGER MULTIPLY/DIVIDE UNIT LATENCIES AND REPEAT RATES

Opcode	Operand Size (mul *rt*) (div *rs*)	Latency	Repeat Rate
`MULT/MULTU, MADD/MADDU, MSUB/MSUBU`	16 bits	1	1
	32 bits	2	2
`MUL`	16 bits	2	1
	32 bits	3	2
`DIV/DIVU`	8 bits	12	11
	16 bits	19	18
	24 bits	26	25
	32 bits	33	32

REGISTER 8-4: UPLLCON: USB PLL CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	R/W-y	R/W-y	R/W-y
	—	—	—	—	—	UPLLODIV<2:0>		
23:16	U-0	U-0	U-0	U-0	U-0	R/W-y	R/W-y	R/W-y
	—	—	—	—	—	UPLLMULT<2:0>		
15:8	U-0	U-0	U-0	U-0	U-0	R/W-y	R/W-y	R/W-y
	—	—	—	—	—	UPLLIDIV<2:0>		
7:0	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—

Legend:	y = Value set from Configuration bits on POR		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-27 **Unimplemented:** Read as ‘`0`’

bit 26-24 **UPLLODIV<2:0>:** USB PLL Output Clock Divider bits

`111` = PLL Divide by 16
`110` = PLL Divide by 12
`101` = PLL Divide by 8
`100` = PLL Divide by 6
`011` = PLL Divide by 4
`010` = PLL Divide by 3
`001` = PLL Divide by 2
`000` = PLL Divide by 1

bit 23-19 **Unimplemented:** Read as ‘`0`’

bit 18-16 **UPLLMULT<2:0>:** USB PLL Multiplier bits

`111` = Multiply by 24
`110` = Multiply by 21
`101` = Multiply by 20
`100` = Multiply by 19
`011` = Multiply by 18
`010` = Multiply by 17
`001` = Multiply by 16
`000` = Multiply by 15

bit 15-11 **Unimplemented:** Read as ‘`0`’

bit 10-8 **UPLLIDIV<2:0>:** USB PLL Input Clock Divider bits

`111` = Divide by 12
`110` = Divide by 10
`101` = Divide by 6
`100` = Divide by 5
`011` = Divide by 4
`010` = Divide by 3
`001` = Divide by 2
`000` = Divide by 1

bit 7-0 **Unimplemented:** Read as ‘`0`’

Note 1: Writes to this register require an unlock sequence. Refer to **Section 42. “Oscillators with Enhanced PLL”** (DS60001250) in the *“PIC32 Family Reference Manual”* for details.

REGISTER 9-4: DCRCCON: DMA CRC CONTROL REGISTER (CONTINUED)

bit 6 **CRCAPP:** CRC Append Mode bit[1]

`1` = The DMA transfers data from the source into the CRC but NOT to the destination. When a block transfer completes the DMA writes the calculated CRC value to the location given by CHxDSA

`0` = The DMA transfers data from the source through the CRC obeying WBO as it writes the data to the destination

bit 5 **CRCTYP:** CRC Type Selection bit

`1` = The CRC module will calculate an IP header checksum
`0` = The CRC module will calculate a LFSR CRC

bit 4-3 **Unimplemented:** Read as ‘`0`’

bit 2-0 **CRCCH<2:0>:** CRC Channel Select bits

`111` = Reserved
`110` = Reserved
`101` = Reserved
`100` = Reserved
`011` = CRC is assigned to Channel 3
`010` = CRC is assigned to Channel 2
`001` = CRC is assigned to Channel 1
`000` = CRC is assigned to Channel 0

Note 1: When WBO = `1`, unaligned transfers are not supported and the CRCAPP bit cannot be set.

REGISTER 9-8: DCHxECON: DMA CHANNEL ‘x’ EVENT CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
	CHAIRQ<7:0>(1)							
15:8	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
	CHSIRQ<7:0>(1)							
7:0	S-0	S-0	R/W-0	R/W-0	R/W-0	U-0	U-0	U-0
	CFORCE	CABORT	PATEN	SIRQEN	AIRQEN	—	—	—

Legend:	S = Settable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-24 **Unimplemented:** Read as ‘0’

bit 23-16 **CHAIRQ<7:0>:** Channel Transfer Abort IRQ bits(1)

11111111 = Interrupt 255 will abort any transfers in progress and set CHAIF flag
•
•
•
00000001 = Interrupt 1 will abort any transfers in progress and set CHAIF flag
00000000 = Interrupt 0 will abort any transfers in progress and set CHAIF flag

bit 15-8 **CHSIRQ<7:0>:** Channel Transfer Start IRQ bits(1)

11111111 = Interrupt 255 will initiate a DMA transfer
•
•
•
00000001 = Interrupt 1 will initiate a DMA transfer
00000000 = Interrupt 0 will initiate a DMA transfer

bit 7 **CFORCE:** DMA Forced Transfer bit

1 = A DMA transfer is forced to begin when this bit is written to a ‘1’
0 = This bit always reads ‘0’

bit 6 **CABORT:** DMA Abort Transfer bit

1 = A DMA transfer is aborted when this bit is written to a ‘1’
0 = This bit always reads ‘0’

bit 5 **PATEN:** Channel Pattern Match Abort Enable bit

1 = Abort transfer and clear CHEN on pattern match
0 = Pattern match is disabled

bit 4 **SIRQEN:** Channel Start IRQ Enable bit

1 = Start channel cell transfer if an interrupt matching CHSIRQ occurs
0 = Interrupt number CHSIRQ is ignored and does not start a transfer

bit 3 **AIRQEN:** Channel Abort IRQ Enable bit

1 = Channel transfer is aborted if an interrupt matching CHAIRQ occurs
0 = Interrupt number CHAIRQ is ignored and does not terminate a transfer

bit 2-0 **Unimplemented:** Read as ‘0’

Note 1: See **Table 7-1: “Interrupt IRQ, Vector and Bit Location”** for the list of available interrupt IRQ sources.

REGISTER 9-12: DCHxSSIZ: DMA CHANNEL ‘x’ SOURCE SIZE REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHSSIZ<15:8>							
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHSSIZ<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as ‘`0`’

bit 15-0 **CHSSIZ<15:0>:** Channel Source Size bits

`1111111111111111` = 65,535 byte source size
•
•
•
`0000000000000010` = 2 byte source size
`0000000000000001` = 1 byte source size
`0000000000000000` = 65,536 byte source size

REGISTER 9-13: DCHxDSIZ: DMA CHANNEL ‘x’ DESTINATION SIZE REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHDSIZ<15:8>							
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHDSIZ<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as ‘`0`’

bit 15-0 **CHDSIZ<15:0>:** Channel Destination Size bits

`1111111111111111` = 65,535 byte destination size
•
•
•
`0000000000000010` = 2 byte destination size
`0000000000000001` = 1 byte destination size
`0000000000000000` = 65,536 byte destination size

REGISTER 9-16: DCHxCSIZ: DMA CHANNEL ‘x’ CELL-SIZE REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHCSIZ<15:8>							
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHCSIZ<7:0>							

Legend:

R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as ‘`0`’

bit 15-0 **CHCSIZ<15:0>:** Channel Cell Size bits

`1111111111111111` = 65,535 bytes transferred on an event
•
•
•
`0000000000000010` = 2 bytes transferred on an event
`0000000000000001`= 1 byte transferred on an event
`0000000000000000` = 65,536 bytes transferred on an event

REGISTER 9-17: DCHxCPTR: DMA CHANNEL ‘x’ CELL POINTER REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
	CHCPTR<15:8>							
7:0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
	CHCPTR<7:0>							

Legend:

R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as ‘`0`’

bit 15-0 **CHCPTR<15:0>:** Channel Cell Progress Pointer bits

`1111111111111111` = 65,535 bytes have been transferred since the last event
•
•
•
`0000000000000001` = 1 byte has been transferred since the last event
`0000000000000000` = 0 bytes have been transferred since the last event

Note: When in Pattern Detect mode, this register is reset on a pattern detect.

REGISTER 10-1: CHECON: CACHE CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
	—	—	—	—	—	—	—	CHECOH
15:8	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
	—	—	—	—	—	—	DCSZ<1:0>	
7:0	U-0	U-0	R/W-0	R/W-0	U-0	R/W-1	R/W-1	R/W-1
	—	—	PREFEN<1:0>		—	PFMWS<2:0>		

Legend:
R = Readable bit W = Writable bit U = Unimplemented bit, read as ‘0’
-n = Value at POR ‘1’ = Bit is set ‘0’ = Bit is cleared x = Bit is unknown

bit 31-17 **Unimplemented:** Write ‘0’; ignore read

bit 16 **CHECOH:** Cache Coherency Setting on a PFM Program Cycle bit
1 = Invalidate all data and instruction lines
0 = Invalidate all data lnes and instruction lines that are not locked

bit 15-10 **Unimplemented:** Write ‘0’; ignore read

bit 9-8 **DCSZ<1:0>:** Data Cache Size in Lines bits
11 = Enable data caching with a size of 4 Lines
10 = Enable data caching with a size of 2 Lines
01 = Enable data caching with a size of 1 Line
00 = Disable data caching
Changing these bits induce all lines to be reinitialized to the “invalid” state.

bit 7-6 **Unimplemented:** Write ‘0’; ignore read

bit 5-4 **PREFEN<1:0>:** Predictive Prefetch Enable bits
11 = Enable predictive prefetch for both cacheable and non-cacheable regions
10 = Enable predictive prefetch for non-cacheable regions only
01 = Enable predictive prefetch for cacheable regions only
00 = Disable predictive prefetch

bit 3 **Unimplemented:** Write ‘0’; ignore read

bit 2-0 **PFMWS<2:0>:** PFM Access Time Defined in Terms of SYSLK Wait States bits
111 = Seven Wait states
110 = Six Wait states
101 = Five Wait states
100 = Four Wait states
011 = Three Wait states
010 = Two Wait states
001 = One Wait state
000 = Zero Wait state

REGISTER 11-12: U1ADDR: USB ADDRESS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	LSPDEN	DEVADDR<6:0>						

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as ‘`0`’

bit 7 **LSPDEN:** Low-Speed Enable Indicator bit
`1` = Next token command to be executed at Low-Speed
`0` = Next token command to be executed at Full-Speed

bit 6-0 **DEVADDR<6:0>:** 7-bit USB Device Address bits

REGISTER 11-13: U1FRML: USB FRAME NUMBER LOW REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
	FRML<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as ‘`0`’

bit 7-0 **FRML<7:0>:** The 11-bit Frame Number Lower bits
The register bits are updated with the current frame number whenever a SOF TOKEN is received.

12.1 Parallel I/O (PIO) Ports

All port pins have 10 registers directly associated with their operation as digital I/O. The data direction register (TRISx) determines whether the pin is an input or an output. If the data direction bit is a '1', then the pin is an input. All port pins are defined as inputs after a Reset. Reads from the latch (LATx) read the latch. Writes to the latch write the latch. Reads from the port (PORTx) read the port pins, while writes to the port pins write the latch.

12.1.1 OPEN-DRAIN CONFIGURATION

In addition to the PORTx, LATx, and TRISx registers for data control, some port pins can also be individually configured for either digital or open-drain output. This is controlled by the Open-Drain Control register, ODCx, associated with each port. Setting any of the bits configures the corresponding pin to act as an open-drain output.

The open-drain feature allows the generation of outputs higher than V_{DD} (e.g., 5V) on any desired 5V-tolerant pins by using external pull-up resistors. The maximum open-drain voltage allowed is the same as the maximum V_{IH} specification.

See the **"Pin Diagrams"** section for the available pins and their functionality.

12.1.2 CONFIGURING ANALOG AND DIGITAL PORT PINS

The ANSELx register controls the operation of the analog port pins. The port pins that are to function as analog inputs must have their corresponding ANSEL and TRIS bits set. In order to use port pins for I/O functionality with digital modules, such as Timers, UARTs, etc., the corresponding ANSELx bit must be cleared.

The ANSELx register has a default value of 0xFFFF; therefore, all pins that share analog functions are analog (not digital) by default.

If the TRIS bit is cleared (output) while the ANSELx bit is set, the digital output level (V_{OH} or V_{OL}) is converted by an analog peripheral, such as the ADC module or Comparator module.

When the PORT register is read, all pins configured as analog input channels are read as cleared (a low level).

Pins configured as digital inputs do not convert an analog input. Analog levels on any pin defined as a digital input (including the ANx pins) can cause the input buffer to consume current that exceeds the device specifications.

12.1.3 I/O PORT WRITE/READ TIMING

One instruction cycle is required between a port direction change or port write operation and a read operation of the same port. Typically this instruction would be a `NOP`.

12.1.4 INPUT CHANGE NOTIFICATION

The input change notification function of the I/O ports allows the PIC32MX1XX/2XX 28/44-pin XLP Family devices to generate interrupt requests to the processor in response to a change-of-state on selected input pins. This feature can detect input change-of-states even in Sleep mode, when the clocks are disabled. Every I/O port pin can be selected (enabled) for generating an interrupt request on a change-of-state.

Five control registers are associated with the CN functionality of each I/O port. The CNENx registers contain the CN interrupt enable control bits for each of the input pins. Setting any of these bits enables a CN interrupt for the corresponding pins.

The CNSTATx register indicates whether a change occurred on the corresponding pin since the last read of the PORTx bit.

Each I/O pin also has a weak pull-up and a weak pull-down connected to it. The pull-ups act as a current source or sink source connected to the pin, and eliminate the need for external resistors when push-button or keypad devices are connected. The pull-ups and pull-downs are enabled separately using the CNPUx and the CNPDx registers, which contain the control bits for each of the pins. Setting any of the control bits enables the weak pull-ups and/or pull-downs for the corresponding pins.

Note: Pull-ups and pull-downs on change notification pins should always be disabled when the port pin is configured as a digital output.

An additional control register (CNCONx) is shown in Register 12-3.

12.2 CLR, SET and INV Registers

Every I/O module register has a corresponding CLR (clear), SET (set) and INV (invert) register designed to provide fast atomic bit manipulations. As the name of the register implies, a value written to a SET, CLR or INV register effectively performs the implied operation, but only on the corresponding base register and only bits specified as '1' are modified. Bits specified as '`0`' are not modified.

Reading SET, CLR and INV registers returns undefined values. To see the affects of a write operation to a SET, CLR, or INV register, the base register must be read.

REGISTER 19-1: SPIxCON: SPI CONTROL REGISTER (CONTINUED)

bit 17 **SPIFE:** Frame Sync Pulse Edge Select bit (Framed SPI mode only)
1 = Frame synchronization pulse coincides with the first bit clock
0 = Frame synchronization pulse precedes the first bit clock

bit 16 **ENHBUF:** Enhanced Buffer Enable bit(2)
1 = Enhanced Buffer mode is enabled
0 = Enhanced Buffer mode is disabled

bit 15 **ON:** SPI Peripheral On bit(1)
1 = SPI Peripheral is enabled
0 = SPI Peripheral is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **SIDL:** Stop in Idle Mode bit
1 = Discontinue module operation when the device enters Idle mode
0 = Continue module operation when the device enters Idle mode

bit 12 **DISSDO:** Disable SDOx pin bit
1 = SDOx pin is not used by the module. Pin is controlled by associated PORT register
0 = SDOx pin is controlled by the module

bit 11-10 **MODE<32,16>:** 32/16-Bit Communication Select bits

When AUDEN = 1:

MODE32	MODE16	Communication
1	1	24-bit Data, 32-bit FIFO, 32-bit Channel/64-bit Frame
1	0	32-bit Data, 32-bit FIFO, 32-bit Channel/64-bit Frame
0	1	16-bit Data, 16-bit FIFO, 32-bit Channel/64-bit Frame
0	0	16-bit Data, 16-bit FIFO, 16-bit Channel/32-bit Frame

When AUDEN = 0:

MODE32	MODE16	Communication
1	x	32-bit
0	1	16-bit
0	0	8-bit

bit 9 **SMP:** SPI Data Input Sample Phase bit
Master mode (MSTEN = 1):
1 = Input data sampled at end of data output time
0 = Input data sampled at middle of data output time
Slave mode (MSTEN = 0):
SMP value is ignored when SPI is used in Slave mode. The module always uses SMP = 0.

To write a '1' to this bit, the MSTEN value = 1 must first be written.

bit 8 **CKE:** SPI Clock Edge Select bit(3)
1 = Serial output data changes on transition from active clock state to Idle clock state (see the CKP bit)
0 = Serial output data changes on transition from Idle clock state to active clock state (see the CKP bit)

bit 7 **SSEN:** Slave Select Enable (Slave mode) bit
1 = $\overline{\text{SSx}}$ pin used for Slave mode
0 = $\overline{\text{SSx}}$ pin not used for Slave mode, pin controlled by port function.

bit 6 **CKP:** Clock Polarity Select bit(4)
1 = Idle state for clock is a high level; active state is a low level
0 = Idle state for clock is a low level; active state is a high level

Note 1: When using the 1:1 PBCLK divisor, the user's software should not read or write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

2: This bit can only be written when the ON bit = 0.

3: This bit is not used in the Framed SPI mode. The user should program this bit to '0' for the Framed SPI mode (FRMEN = 1).

4: When AUDEN = 1, the SPI module functions as if the CKP bit is equal to '1', regardless of the actual value of CKP.

REGISTER 24-1: AD1CON1: ADC CONTROL REGISTER 1 (CONTINUED)

bit 4 **CLRASAM:** Stop Conversion Sequence bit (when the first ADC interrupt is generated)
1 = Stop conversions when the first ADC interrupt is generated. Hardware clears the ASAM bit when the ADC interrupt is generated.
0 = Normal operation, buffer contents will be overwritten by the next conversion sequence

bit 3 **Unimplemented:** Read as '0'

bit 2 **ASAM:** ADC Sample Auto-Start bit
1 = Sampling begins immediately after last conversion completes; SAMP bit is automatically set.
0 = Sampling begins when SAMP bit is set

bit 1 **SAMP:** ADC Sample Enable bit(2)
1 = The ADC sample and hold amplifier is sampling
0 = The ADC sample/hold amplifier is holding
When ASAM = 0, writing '1' to this bit starts sampling.
When SSRC = 000, writing '0' to this bit will end sampling and start conversion.

bit 0 **DONE:** Analog-to-Digital Conversion Status bit(3)
1 = Analog-to-digital conversion is done
0 = Analog-to-digital conversion is not done or has not started
Clearing this bit will not affect any operation in progress.

Note 1: When using 1:1 PBCLK divisor, the user's software should not read/write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

2: If ASAM = 0, software can write a '1' to start sampling. This bit is automatically set by hardware if ASAM = 1. If SSRC = 0, software can write a '0' to end sampling and start conversion. If SSRC ≠ '0', this bit is automatically cleared by hardware to end sampling and start conversion.

3: This bit is automatically set by hardware when analog-to-digital conversion is complete. Software can write a '0' to clear this bit (a write of '1' is not allowed). Clearing this bit does not affect any operation already in progress. This bit is automatically cleared by hardware at the start of a new conversion.

REGISTER 28-1: CTMUCON: CTMU CONTROL REGISTER (CONTINUED)

bit 10 **EDGSEQEN:** Edge Sequence Enable bit

`1` = Edge1 must occur before Edge2 can occur
`0` = No edge sequence is needed

bit 9 **IDISSEN:** Analog Current Source Control bit(2)

`1` = Analog current source output is grounded
`0` = Analog current source output is not grounded

bit 8 **CTTRIG:** Trigger Control bit

`1` = Trigger output is enabled
`0` = Trigger output is disabled

bit 7-2 **ITRIM<5:0>:** Current Source Trim bits

`011111` = Maximum positive change from nominal current
`011110`
•
•
•
`000001` = Minimum positive change from nominal current
`000000` = Nominal current output specified by IRNG<1:0>
`111111` = Minimum negative change from nominal current
•
•
•
`100010`
`100001` = Maximum negative change from nominal current

bit 1-0 **IRNG<1:0>:** Current Range Select bits(3)

`11` = 100 times base current
`10` = 10 times base current
`01` = Base current level
`00` = 1000 times base current(4)

Note 1: When this bit is set for Pulse Delay Generation, the EDG2SEL<3:0> bits must be set to ‘`1110`’ to select C2OUT.

2: The ADC module Sample and Hold capacitor is not automatically discharged between sample/conversion cycles. Software using the ADC as part of a capacitive measurement, must discharge the ADC capacitor before conducting the measurement. The IDISSEN bit, when set to ‘`1`’, performs this function. The ADC module must be sampling while the IDISSEN bit is active to connect the discharge sink to the capacitor array.

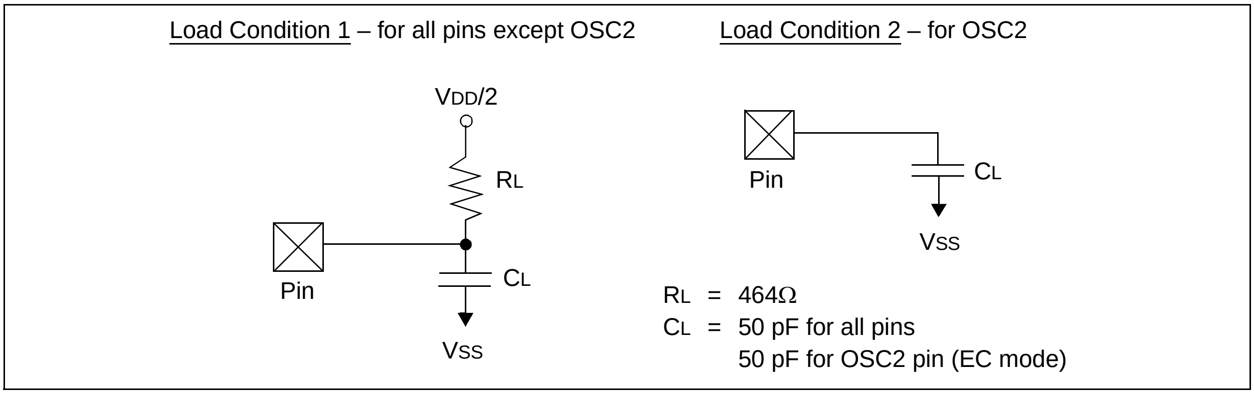
3: Refer to the CTMU Current Source Specifications (Table 33-42) in **33.0 “Electrical Characteristics”** for current values.

4: This bit setting is not available for the CTMU temperature diode.

33.2 AC Characteristics and Timing Parameters

The information contained in this section defines PIC32MX1XX/2XX 28/44-pin XLP Family AC characteristics and timing parameters.

FIGURE 33-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS



RL = 464Ω
CL = 50 pF for all pins
50 pF for OSC2 pin (EC mode)

TABLE 33-17: CAPACITIVE LOADING REQUIREMENTS ON OUTPUT PINS

AC CHARACTERISTICS			**Standard Operating Conditions: 2.5V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical$^{(1)}$**	**Max.**	**Units**	**Conditions**
DO50	COSCO	OSC2 pin	—	—	15	pF	In XT and HS modes when an external crystal is used to drive OSC1
DO56	CIO	All I/O pins and OSC2	—	—	50	pF	EC mode
DO58	CB	SCLX, SDAX	—	—	400	pF	In I^{2}C mode

Note 1: Data in “Typical” column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

FIGURE 33-2: EXTERNAL CLOCK TIMING

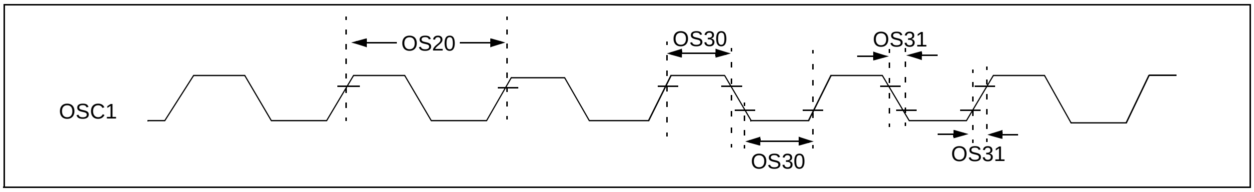


TABLE 33-34: I2Cx BUS DATA TIMING REQUIREMENTS (SLAVE MODE) (CONTINUED)

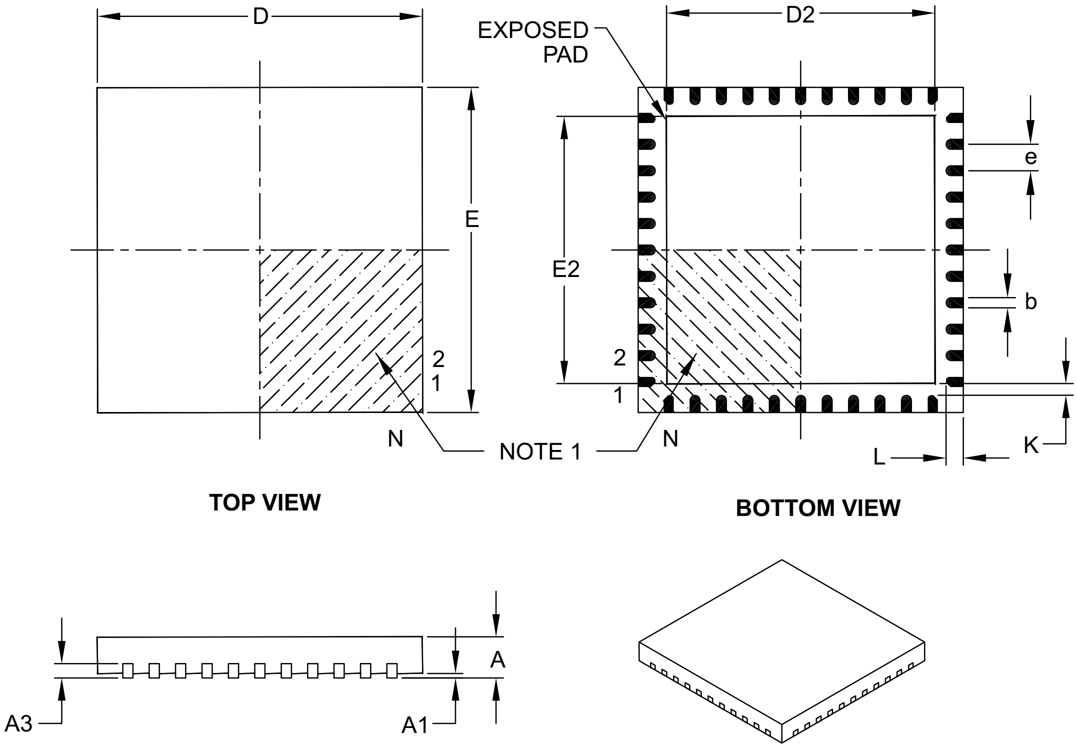
AC CHARACTERISTICS				**Standard Operating Conditions: 2.5V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp			
Param. No.	**Symbol**	**Characteristics**		**Min.**	**Max.**	**Units**	**Conditions**
IS34	THD:STO	Stop Condition Hold Time	100 kHz mode	4000	—	ns	—
			400 kHz mode	600	—	ns	
			1 MHz mode **(Note 1)**	250		ns	
IS40	TAA:SCL	Output Valid from Clock	100 kHz mode	0	3500	ns	—
			400 kHz mode	0	1000	ns	
			1 MHz mode **(Note 1)**	0	350	ns	
IS45	TBF:SDA	Bus Free Time	100 kHz mode	4.7	—	μs	The amount of time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	μs	
			1 MHz mode **(Note 1)**	0.5	—	μs	
IS50	CB	Bus Capacitive Loading		—	400	pF	—

Note 1: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

NOTES:

44-Lead Plastic Quad Flat, No Lead Package (ML) – 8x8 mm Body [QFN]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



TOP VIEW

BOTTOM VIEW

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	44		
Pitch	e	0.65 BSC		
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3	0.20 REF		
Overall Width	E	8.00 BSC		
Exposed Pad Width	E2	6.30	6.45	6.80
Overall Length	D	8.00 BSC		
Exposed Pad Length	D2	6.30	6.45	6.80
Contact Width	b	0.25	0.30	0.38
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	–	–

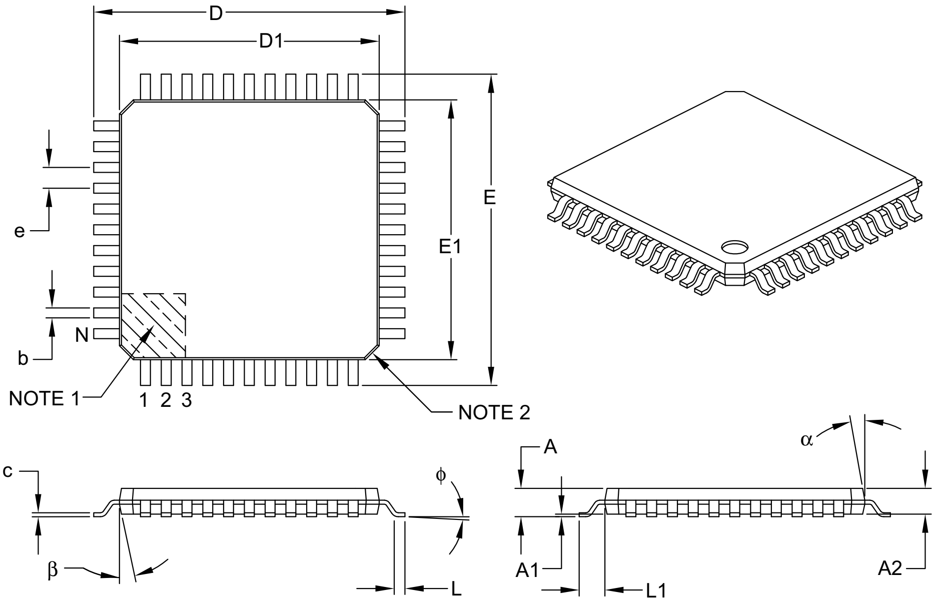
Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-103B

44-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N	44		
Lead Pitch	e	0.80 BSC		
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1	1.00 REF		
Foot Angle	φ	0°	3.5°	7°
Overall Width	E	12.00 BSC		
Overall Length	D	12.00 BSC		
Molded Package Width	E1	10.00 BSC		
Molded Package Length	D1	10.00 BSC		
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.30	0.37	0.45
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-076B